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DECLARATION

As a below named inventor(s), I (we) hereby declare that:

My (our) residence, post office address and citizenship are as stated below next to my (our) name;

I (we) believe I (we) am (are) the original, first and sole inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled A NEW APPROACH TO AVOID BUCKLING IN BPSG BY USING AN INTERMEDIATE BARRIER LAYER; the specification of which is attached hereto;

I (we) hereby state that I (we) have reviewed and understand the contents of the above identified specification, including the claims;

I (we) acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations Section 1.56(a);

I (we) hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign applications(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed;

I (we) hereby claim the benefit under Title 35, United States Code Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I (we) acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application;

I (we) hereby declare that all statements made of my (our) own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon;

POWER OF ATTORNEY: As a named inventor, I appoint the following as attorney(s)/agent(s) to transact all business in the Patent and Trademark Office for this application, Angus C. Fox, III, (Registration #31,828), Stanley N. Protigal, (Registration #28,657), David J. Paul (Registration No. 34,692), Susan B. Collier (Registration No. 34,566), Lia M. Pappas (Registration No. 34,095), Michael W. Starkweather (Registration #34,441), William R. Bachand (Registration No. 34,980), Ozer M. N. Teitelbaum (Registration No. P36, 698).

Send Correspondence to: Ozer M. N. Teitelbaum, Patent Attorney
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2805 East Columbia Road
Boise, Idaho 83706
Tel. 208-368-4543

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(First) (MI) (Last)

Inventor's Signature:  Date: 3/17/93

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Inventor's Full Name: Randhir P. S. Thakur
(First) (MI) (Last)

Inventor's Signature:  Date: 3-17-93

Citizenship: India

Post Office Address: 1594 Riverstone Lane

Boise, Idaho 83706

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Inventor's Full Name: Yauh-Ching Liu
(First) (MI) (Last)

Inventor's Signature: Yauh-Ching Liu Date: 3/19/93

Citizenship: Taiwan, Republic of China

Post Office Address: 9226 West Susan Street

Boise, Idaho 83704

City, State and
Country of Residence Boise, Idaho, United States of America

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Mr. T. Doan
Mr. P.S. Thakur
Mr. Ching Liu

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Security Agreement ☐ Change of Name

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Execution Date: 03/17-19/93

2. Name and address of receiving party(ies):

Name: Micron Semiconductor, Inc.

Internal Address: Patent Department, MS 507

Street Address: 2805 E. Columbia Rd.

City: Boise State: ID ZIP: 83706

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Identification number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

Continuation of Serial No.: 08/034,339
Sheet 92-321.1

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

4. Name and address of party to whom correspondence concerning document should be mailed:

Mr. Lia M. Pappas

Internal Address: Patent Department

MS 507

Address: 2805 E. Columbia Road

Boise State: ID ZIP: 83706

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):..... \$ 40.00

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Lia M. Pappas
Name of Person Signing

Lia M. Pappas

August 23, 1994

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Randhir P.S. Thakur
Yauh-Ching Liu

2. Name and address of receiving party:

Micron Semiconductor, Inc.
2805 E. Columbia Rd. MS 507
Boise, ID 83706-9698

3. Nature of conveyance:

☒ OTHER: CORRECTIVE ASSIGNMENT
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Related to Application
Serial Number: 08/034,339
Filing Date: March 19, 1993
Docket Number: 92-321

B. Patent Number(s)

☐ Additional numbers attached

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5. Name and address of party to whom correspondence concerning document should be mailed:

William R. Bachand
Micron Semiconductor, Inc.
2805 East Columbia Rd. MS 507
Boise, ID 83706-9698

6. Total number of applications and patents involved: 1

7. Total Fee (37 CFR 1.22(h))

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William R. BACHAND

Print name of person signing

William R Bachand 2/2/94

Signature

Date

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Name of conveying party(ies):
Doan
Randh P.S. Thakur
Yauh-Ching Liu

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

Nature of conveyance:

X Assignment ☒ Merger

Security Agreement ☐ Change of Name

Other _____

Execution Date: 3/19/93

Name and address of receiving party(ies):

Name: Micron Semiconductor Inc

Internal Address: MS# 507

Street Address: 2805 E. Columbia Rd.

City: Boise State: ID ZIP: 83706

Additional name(s) & address(es) attached? ☐ Yes ☐ No

Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 3/19/93

A. Patent Application No.(s)

Attached Application
Docket #92-321

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☐ No

Name and address of party to whom correspondence concerning document should be mailed:

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Patent Department

Street Address: 2805 E. Columbia Rd

City: Boise State: Id ZIP: 83706

6. Total number of applications and patents involved:

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Trung T. Doan
Randhir P.S. Thakur
Yauh-Ching Liu

Docket No.: 92-321

Group Art Unit:

Examiner:

Serial No:

Filed: Concurrently herewith

For: A NEW APPROACH TO AVOID
BUCKLING IN BPSG BY USING
AN INTERMEDIATE BARRIER
LAYER

ASSIGNMENT:

Enclosed for recording
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Date: _____
Reel: _____

A S S I G N M E N T

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned, do hereby:

YC Lin 1/24/94 *Mon 1-24/94* *Idaho* *1-13-94*
SELL, ASSIGN AND TRANSFER to Micron Semiconductor, Inc. (the "Assignee"), a corporation of ~~Delaware~~ *Idaho*, having a place of business at 2805 E. Columbia Road, Boise, Idaho 83706, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled: A NEW APPROACH TO AVOID BUCKLING IN BPSG BY USING AN INTERMEMEDIATE BARRIER LAYER; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States;

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AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.


(Signature)


Trung T. Doan

Date:

3/17/93

(Signature)


Randhir P.S. Thakur

Date:

3-17-93

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0077

NEEL

FRANK

65745 FRANK

(Signature) Yauh-Ching Liu Date: 3/19/93
Yauh-Ching Liu

STATE OF IDAHO)
) ss.
County of Ada)

BEFORE ME, this 19 day of March 1993
personally appeared the above-named individual(s), to me known to
be the person(s) who is (are) described in and who executed the
foregoing assignment instrument and acknowledged to me that he/she
(they) executed the same of his/her (their) own free will for the
purpose therein expressed.

SEAL

Deanne Schuda
Notary or Consular Officer
My Commission Expires: 6/27/96

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